02 993,266

Abstract of the Disclosure:

An electronic component with shielding is described. component has a semiconductor chip with a semiconductor substrate. Disposed in a region of a rear side of the semiconductor substrate is an electrically conductive buried The buried layer is connected via a ground lead, disposed within the semiconductor substrate, to a contact area and an external ground potential. Furthermore, the invention relates to a method for producing an electronic component of 10 this type.

١D Q Q m

5

REL/cp